March 2010

BS170 / MMBF170 N-Channel Enhancement Mode Field Effect Transistor

General Description

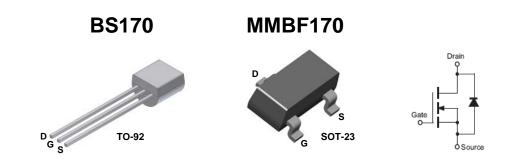
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These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 500mA DC. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

- High density cell design for low R_{DS(ON)}.
- Voltage controlled small signal switch.
- Rugged and reliable.
- High saturation current capability.



Absolute Maximum Ratings $T_A = 25^{\circ}C$ unless otherwise noted

| Symbol | Parameter | BS170 | MMBF170 | Units | |
|-----------------------------------|--|---------------|---------|-------|--|
| V _{DSS} | Drain-Source Voltage | 60 | | V | |
| V _{DGR} | Drain-Gate Voltage ($R_{GS} \le 1M\Omega$) | 60 | | V | |
| V _{GSS} | Gate-Source Voltage | ± 20 | | V | |
| ۱ _D | Drain Current - Continuous | 500 | 500 | mA | |
| | - Pulsed | - Pulsed 1200 | | | |
| T _J , T _{STG} | Operating and Storage Temperature Range | - 55 to 150 | | °C | |
| Τ _L | Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds | 300 | | °C | |

Thermal Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

| ſ | Symbol | Parameter | BS170 | MMBF170 | Units |
|---|---------------------|--|------------|------------|-------------|
| | PD | Maximum Power Dissipation Derate above 25°C | 830 6.6 | 300 2.4 | mW mW/°C |
| | $R_{	ext{	heta}JA}$ | Thermal Resistance, Junction to Ambient | 150 | 417 | °C/W |

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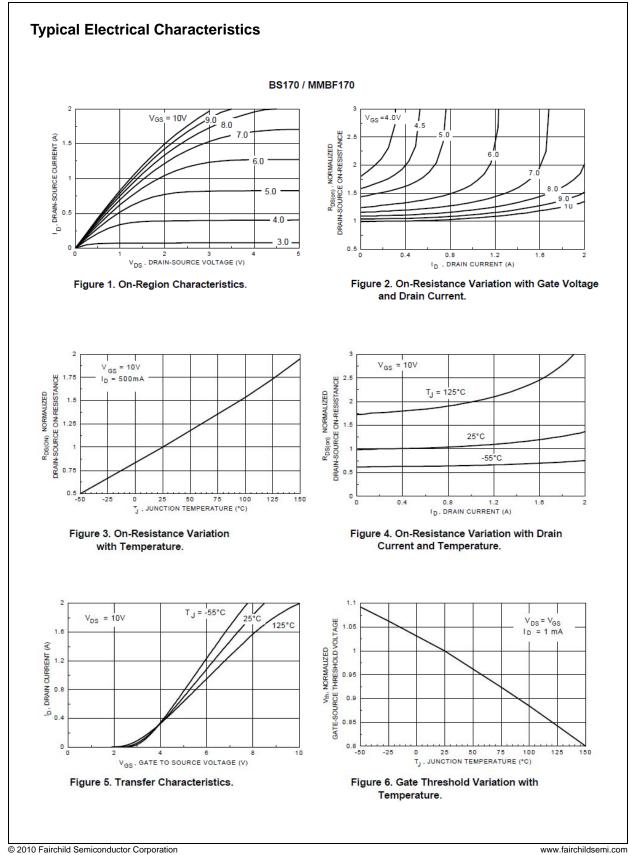
| Symbol | Parameter | Conditions | Туре | Min. | Тур. | Max. | Units |
|---------------------|-----------------------------------|--|---------|------|------|------|----------|
| OFF CHA | RACTERISTICS | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_{D} = 100\mu A$ | All | 60 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 25V, V_{GS} = 0V$ | All | | | 0.5 | μΑ |
| I _{GSSF} | Gate - Body Leakage, Forward | $V_{GS} = 15V, V_{DS} = 0V$ | All | | | 10 | nA |
| ON CHAF | RACTERISTICS (Notes 1) | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 1mA$ | All | 0.8 | 2.1 | 3 | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance | $V_{GS} = 10V, I_D = 200mA$ | All | | 1.2 | 5 | Ω |
| 9 _{FS} | Forward Transconductance | V _{DS} = 10V, I _D = 200mA | BS170 | | 320 | | mS |
| | | | MMBF170 | | 320 | |] |
| Dynamic | Characteristics | | | | • | | <u> </u> |
| C _{iss} | Input Capacitance | $V_{DS} = 10V, V_{GS} = 0V,$ | All | | 24 | 40 | pF |
| C _{oss} | Output Capacitance | f = 1.0MHz | All | | 17 | 30 | pF |
| C _{rss} | Reverse Transfer Capacitance | | All | | 7 | 10 | pF |
| Switching | g Characteristics (Notes 1) | | | | • | | · |
| t _{on} | Turn-On Time | $\label{eq:VDD} \begin{array}{l} V_{\text{DD}} = 25V, \ I_{\text{D}} = 200mA, \\ V_{\text{GS}} = 10V, \ R_{\text{GEN}} = 25\Omega \end{array}$ | BS170 | | | 10 | ns |
| | | $V_{DD} = 25V, I_D = 500mA, \\ V_{GS} = 10V, R_{GEN} = 50\Omega$ | MMBF170 | | | 10 |] |
| t _{off} | Turn-Off Time | $V_{\text{DD}} = 25\text{V}, \text{ I}_{\text{D}} = 200\text{mA}, \\ V_{\text{GS}} = 10\text{V}, \text{ R}_{\text{GEN}} = 25\Omega$ | BS170 | | | 10 | ns |
| | | V_{DD} = 25V, I_D = 500mA, V_{GS} = 10V, R_{GEN} = 50 Ω | MMBF170 | | | 10 | 1 |

Note:

1. Pulse Test: Pulse Width $\leq~300\mu s,$ Duty Cycle $\leq 2.0\%.$

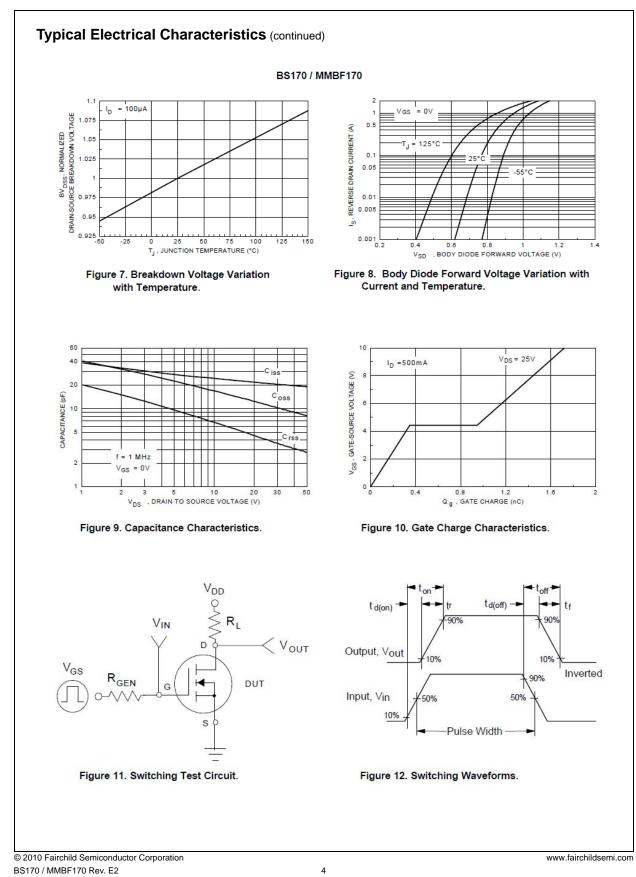
Ordering Information

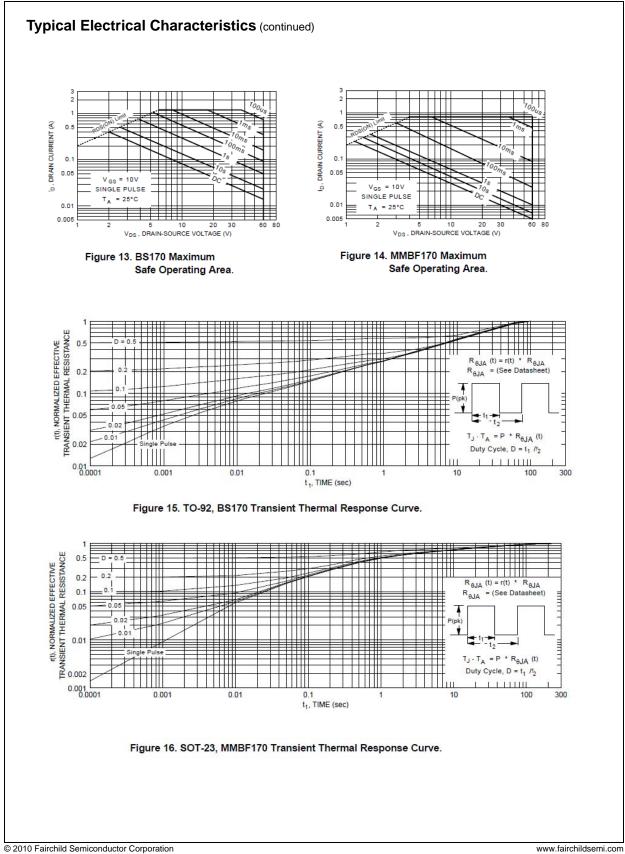
| Part Number | Package | Package Type | Lead Frame | Pin array |
|-------------|---------|---------------|------------|-----------|
| BS170 | TO-92 | BULK | STRAIGHT | DGS |
| BS170_D26Z | TO-92 | Tape and Reel | FORMING | DGS |
| BS170_D27Z | TO-92 | Tape and Reel | FORMING | DGS |
| BS170_D74Z | TO-92 | AMMO | FORMING | DGS |
| BS170_D75Z | TO-92 | AMMO | FORMING | DGS |
| MMBF170 | SOT-23 | Tape and Reel | | |



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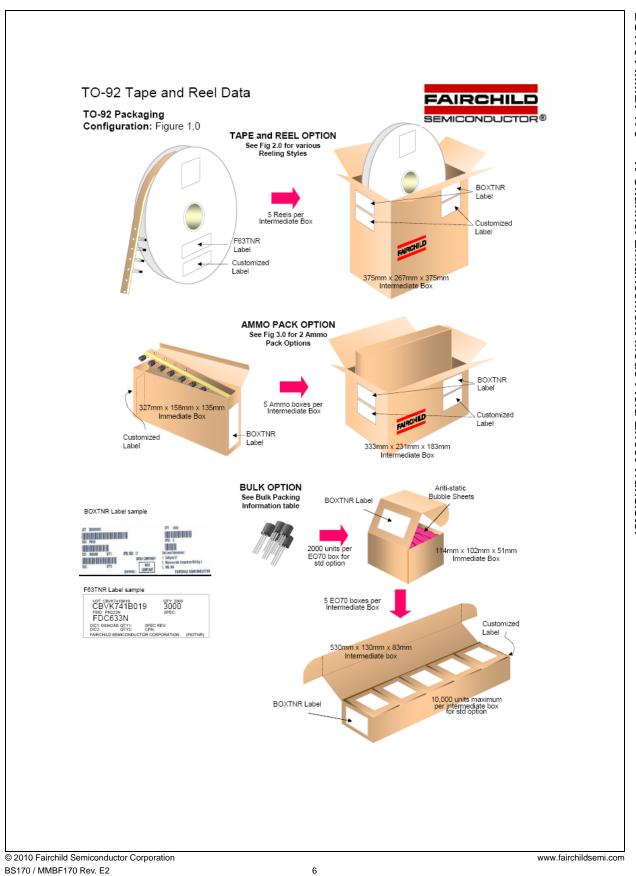
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TO-92 Tape and Reel Data, continued



TO-92 Packing Information: Figure 2.0

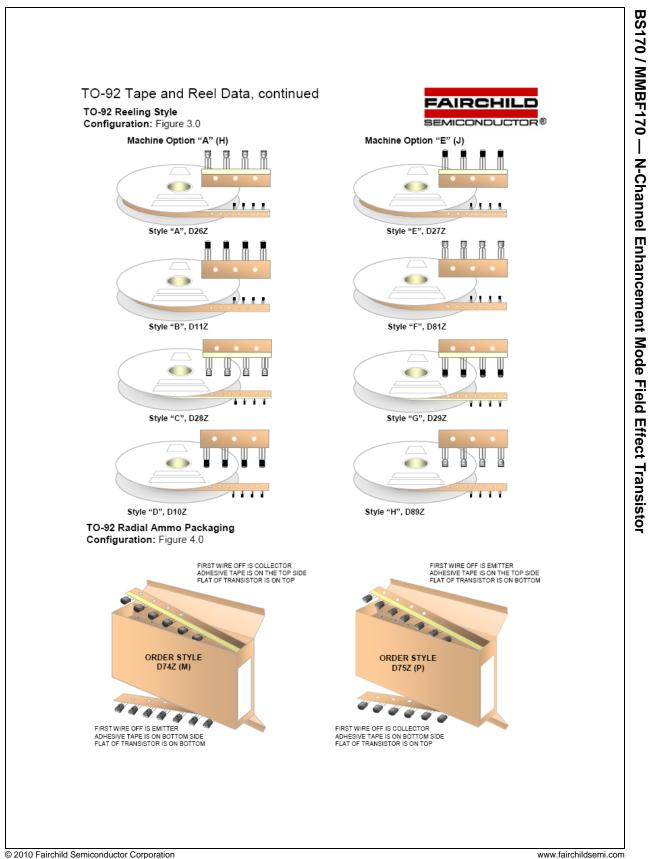
| Packing | Style | Quantity | EOL code |
|---------------|-----------------------------|---|----------|
| Reel | A | 2,000 | D26Z |
| | В | 2,000 | D11Z |
| | С | 2,000 | D28Z |
| | D | 2,000 | D10Z |
| | E | 2,000 | D27Z |
| | F | 2,000 | D81Z |
| | G | 2,000 | D29Z |
| | н | 2,000 | D89Z |
| Ammo | М | 2,000 | D74Z |
| | Р | 2,000 | D75Z |
| mmo weight wi | components th components | = 0.22 gm = 1.04 kg = 1.02 kg x = 10.000 units | |

TO-92 BULK PACKING INFORMATION TABLE

| EOL CODE / FLOW OPTION | DESCRIPTION | LEADCLIP DIMENSION | MINIMUM ORDER QTY | LEADFORM OULTINE |
|------------------------------|-------------------------|-----------------------|----------------------|---------------------|
| NO EOL CODE | STRAIGHT LEADS | NO LEAD CLIP | 2.0K / BOX | × |
| J18Z | TO-18 OPTION STD | NO LEAD CLIP | 2.0K / BOX | |
| J35Z | TO-18 OPTION REVERSE | NO LEAD CLIP | 2.0K / BOX | |
| J05Z | TO-5 OPTION STD | NO LEAD CLIP | 1.5K / BOX | |
| J60Z | TO-5 OPTION REVERSE | NO LEAD CLIP | 1.5K / BOX | |
| J61Z | IN LINE 0.200 SPACING | NO LEAD CLIP | 1.5K / BOX | |

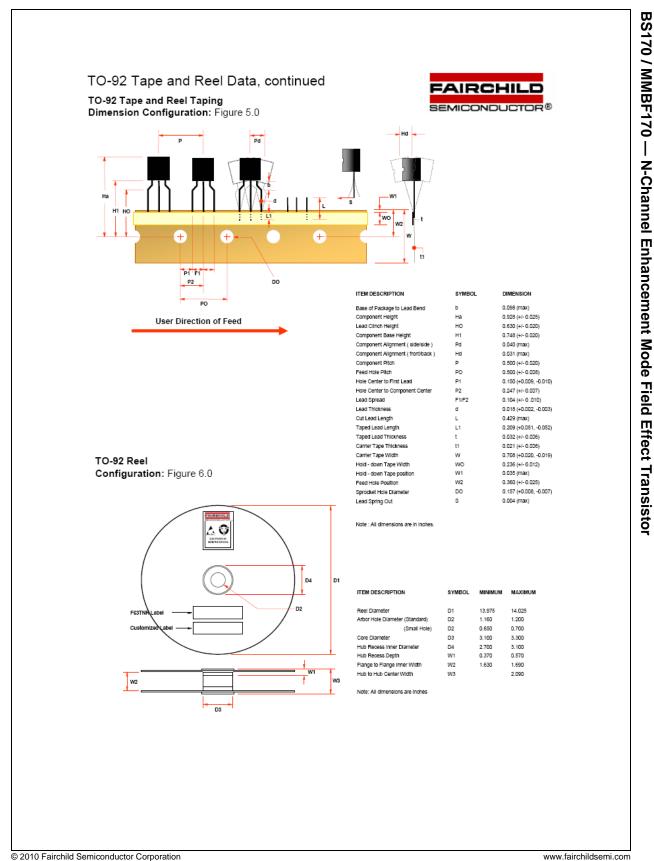
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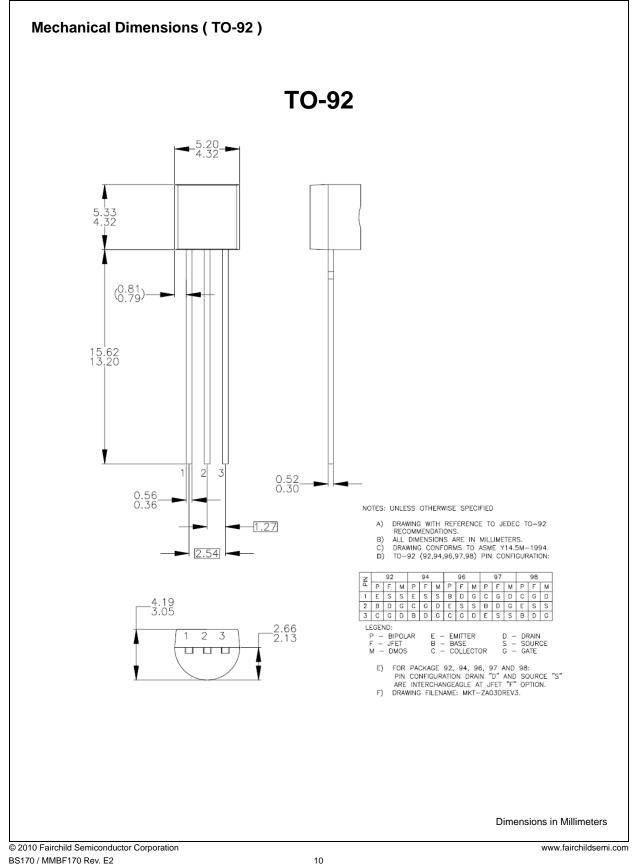


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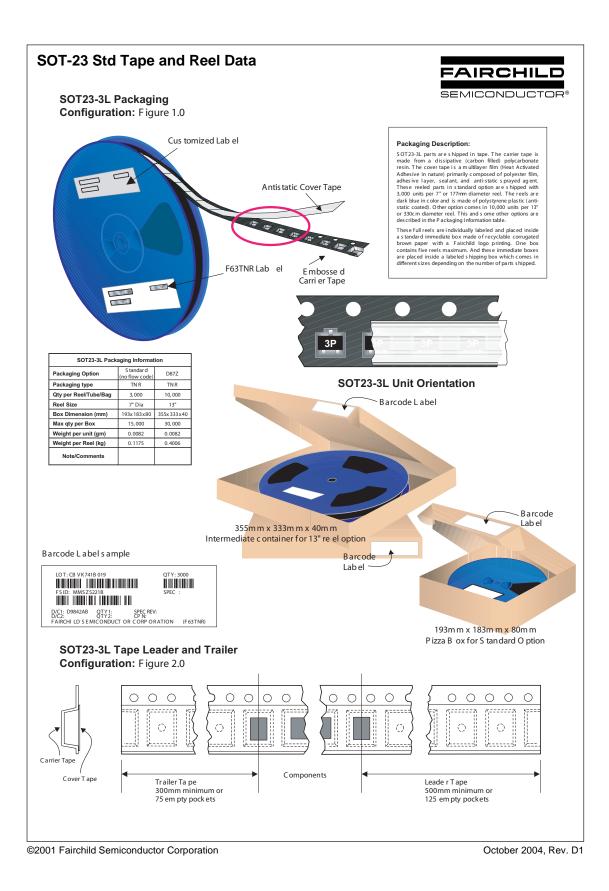
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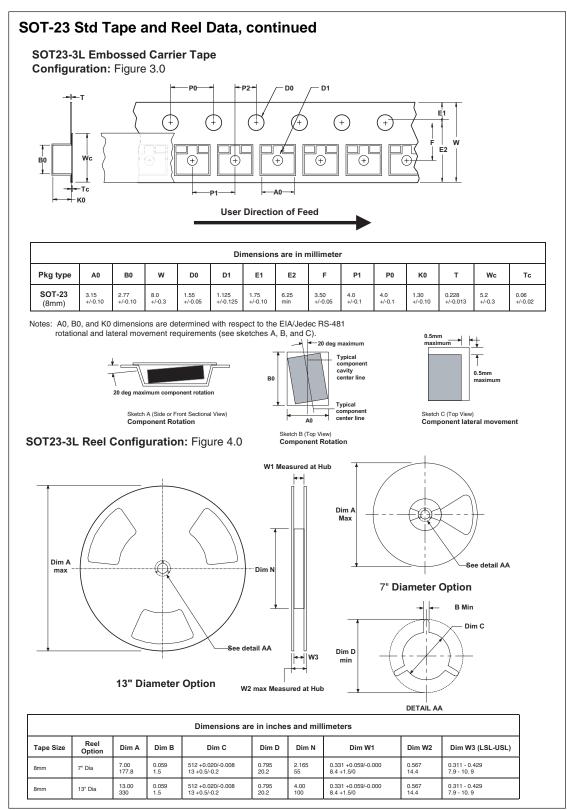
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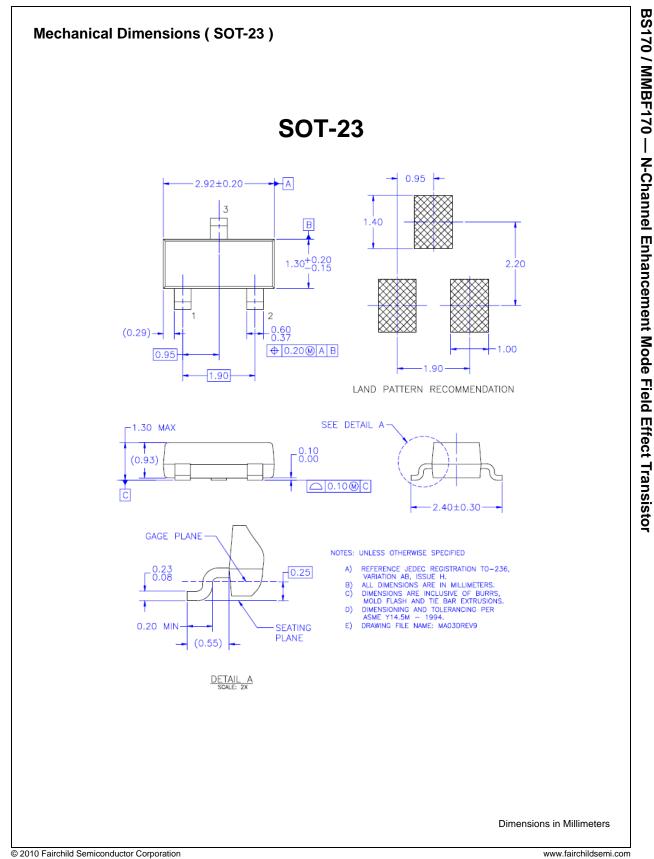
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October 2004, Rev. D1



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Definition of Term

| Product Status | Definition |
|-----------------------|---|
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| First Production | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| Full Production | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design. |
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| | Formative / In Design First Production Full Production |

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